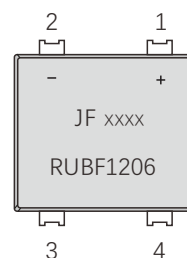


UBF

FEATURES:

- Glass Passivated Chip Junction
- Reverse Voltage - 600 V
- Forward Current - 12.0 A
- Fast reverse recovery time
- Designed for Surface Mount Application

HALOGEN
FREE

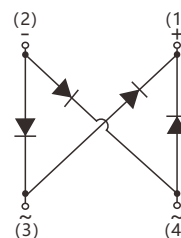


Marking:

JF:Logo
xxxx:Date code
RUBF1206:Type
+ -:Polarity

MECHANICAL DATA

- Case: UBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.461g / 0.0163oz



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

PARAMETER	SYMBOL	RUBF1206	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	600	V
Maximum RMS voltage	V_{RMS}	420	V
Maximum DC Blocking Voltage	V_{DC}	600	V
Average Rectified Output Current	I_o	12.0	A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	350	A
I^2t Rating for Fusing ($t=8.3ms$)	I^2t	508	A ² S
Typical Thermal Resistance ⁽¹⁾	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	60 4 14	°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

(1) Mounted on glass epoxy PC board with 4 X 1.5" X 1.5" (3.81X3.81cm) copper pad

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

PARAMETER	SYMBOL	TEST CONDITIONS	TYP	MAX	Units
Instantaneous forward voltage	V_F	$I_F=6A$ $T_j=25^\circ C$ $I_F=12A$ $T_j=25^\circ C$	—	1.00 1.30	V
Reverse current at DC blocking voltage	I_R	$T_j=25^\circ C$ $T_j=125^\circ C$	—	5 100	uA
Maximum Reverse Recovery Time	t_{rr}	Measured with $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$	—	300	ns
Typical Junction Capacitance	C_j	$f=1MHz, V_R=4VDC$ $T_j=25^\circ C$	73	—	pF

Fig.1 Average Rectified Output Current Derating Curve

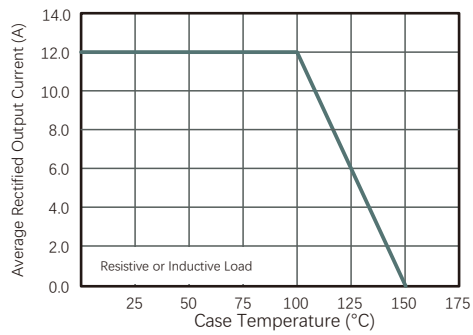


Fig.2 Typical Reverse Characteristics

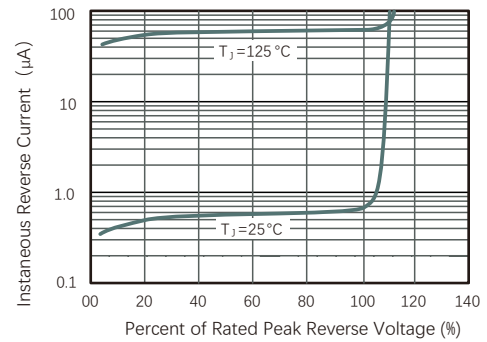


Fig.3 Typical Instantaneous Forward Characteristics

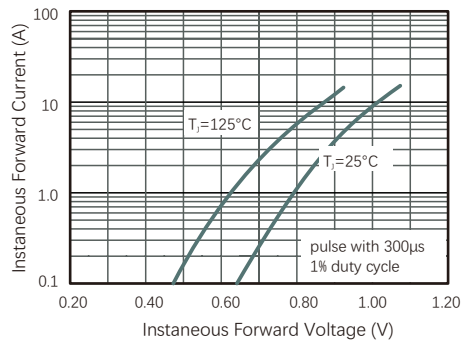


Fig.4 Typical Junction Capacitance

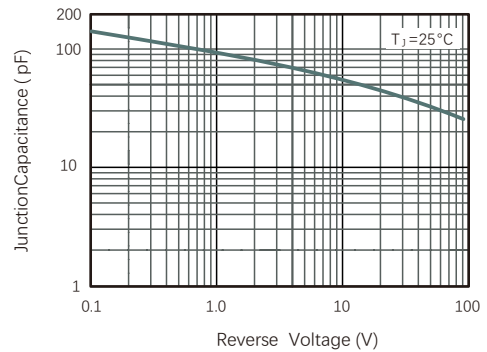


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

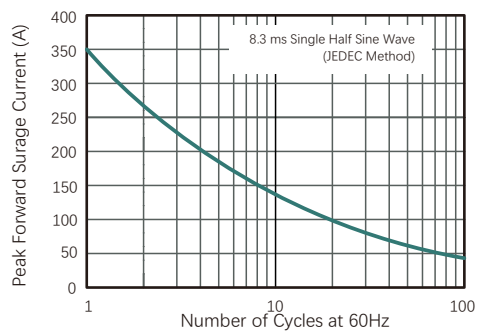
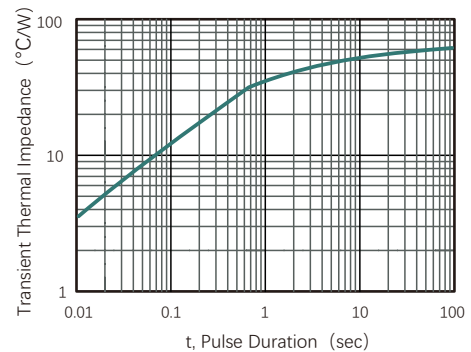
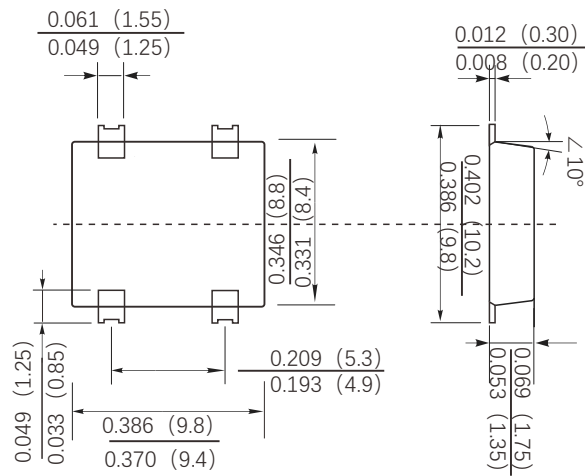


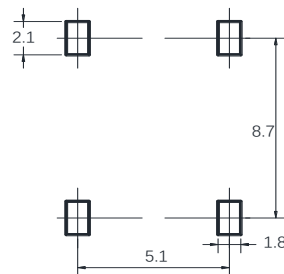
Fig.6- Typical Transient Thermal Impedance



UBF



Suggested solder pad layout



(设计者可参考推荐值根据焊接工艺要求自行确定适合的焊盘尺寸)
(Designers can refer to the recommended values according to the manufacturing process requirements to determine the appropriate pad size)

Dimensions in millimeters

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